Build Up HDI (Standard)

HDI08_1+6+1_0,90_35_engl

8 - Layers

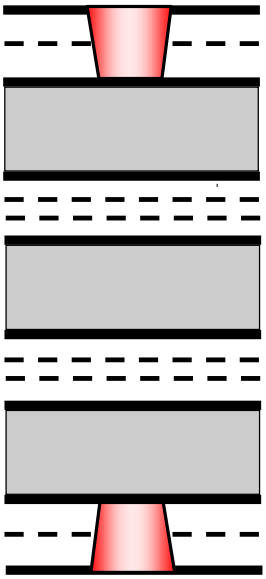
Core: 0,10 mm Cu 35/35 µm

WE-Articel No.:

1 + 6 + 1

Customer:

WÜRTH ELEKTRONIK

layer description		configuration	Raw-Material	CU	PREPREG	Final Thickness	Customer requirements
Customer	WE					[µm]	[µm]
	TOP/VS		Foil	12 µm		12	
					1 x 1080	**60**	
	2			35 µm		**33**	
			0,100 mm			**100**	
	3			35 µm		**33**	
					2 x 1080	**124**	
	4			35 µm		**33**	
			0,100 mm			**100**	
	5			35 µm		**33**	
					2 x 1080	**124**	
	6			35 µm		**33**	
			0,100 mm			**100**	
	7			35 µm		**33**	
					1 x 1080	**60**	
	BOT/RS		Foil	12 µm		**12**	

1) copper thickness outer layers: appr. 55 µm

total material thickness: 890

Note: Lamination thickness for Prepregs depending on layout characteristics.

final lamination thickness:	**0,90**	+/-	0,07	mm		Date:	Engineer:
thickness with electro plated Cu:	0,99	+/-	0,10	mm			
total thickness with soldermask	1,05	+/-	0,12	mm			
customer requirement		+/-		mm	point:		

prepared: on	by	checked: on	by	approved: on	by	revision		
25.04.2006	**S. Keller**	04.05.2006	M.Kress	25.04.2006	R. Schönholz	00	page:	4+